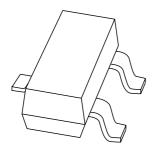
## **DISCRETE SEMICONDUCTORS**

# DATA SHEET



## BCW29; BCW30 PNP general purpose transistors

Product data sheet Supersedes data of 1999 Apr 13 2004 Jan 13



## PNP general purpose transistors

**BCW29; BCW30** 

#### **FEATURES**

• Low current (max. 100 mA)

• Low voltage (max. 32 V).

#### **APPLICATIONS**

• General purpose switching and amplification.

#### **DESCRIPTION**

PNP transistor in a SOT23 plastic package. NPN complements: BCW31 and BCW32.

#### **MARKING**

TYPE NUMBER	MARKING CODE <sup>(1)</sup>
BCW29	C1*
BCW30	C2*

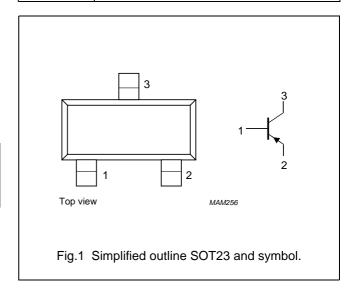
#### Note

1. \* = p: Made in Hong Kong.

\* = t : Made in Malaysia. \* = W : Made in China.

#### **PINNING**

PIN	DESCRIPTION
1	base
2	emitter
3	collector



#### **ORDERING INFORMATION**

TYPE	PACKAGE						
NUMBER	NAME	DESCRIPTION	VERSION				
BCW29	_	plastic surface mounted package; 3 leads	SOT23				
BCW30							

#### **LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>CBO</sub>	collector-base voltage	open emitter	_	-32	V
V <sub>CEO</sub>	collector-emitter voltage	open base; I <sub>C</sub> = −2 mA	_	-32	V
V <sub>EBO</sub>	emitter-base voltage	open collector	_	-5	V
I <sub>C</sub>	collector current (DC)		_	-100	mA
I <sub>CM</sub>	peak collector current		_	-200	mA
I <sub>BM</sub>	peak base current		_	-200	mA
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C	_	250	mW
T <sub>stg</sub>	storage temperature		-65	+150	°C
Tj	junction temperature		_	150	°C
T <sub>amb</sub>	operating ambient temperature		-65	+150	°C

## PNP general purpose transistors

BCW29; BCW30

#### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient	note 1	500	K/W

#### Note

1. Transistor mounted on an FR4 printed-circuit board.

#### **CHARACTERISTICS**

 $T_i = 25$  °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I <sub>CBO</sub>	collector cut-off current	$I_E = 0$ ; $V_{CB} = -32 \text{ V}$	_	_	-100	nA
		$I_E = 0$ ; $V_{CB} = -32 \text{ V}$ ; $T_j = 100 ^{\circ}\text{C}$	_	_	-10	μΑ
I <sub>EBO</sub>	emitter cut-off current	$I_C = 0; V_{EB} = -5 \text{ V}$	_	_	-100	nA
h <sub>FE</sub>	DC current gain	$I_C = -10 \mu A; V_{CE} = -5 V$				
	BCW29		_	90	-	
	BCW30		_	150	_	
	DC current gain	$I_C = -2 \text{ mA}; V_{CE} = -5 \text{ V}$				
	BCW29		120	-	260	
	BCW30		215	_	500	
V <sub>CEsat</sub>	collector-emitter saturation	$I_C = -10 \text{ mA}; I_B = -0.5 \text{ mA}$	_	-80	-300	mV
	voltage	$I_C = -50 \text{ mA}; I_B = -2.5 \text{ mA}$	_	-150	_	mV
V <sub>BEsat</sub>	base-emitter saturation voltage	$I_C = -10 \text{ mA}; I_B = -0.5 \text{ mA}$	_	-720	_	mV
		$I_C = -50 \text{ mA}; I_B = -2.5 \text{ mA}$	_	-810	_	mV
V <sub>BE</sub>	base-emitter voltage	$I_C = -2 \text{ mA}; V_{CE} = -5 \text{ V}$	-600	_	-750	mV
C <sub>c</sub>	collector capacitance	$I_E = I_e = 0$ ; $V_{CB} = -10 \text{ V}$ ; $f = 1 \text{ MHz}$	_	4.5	_	pF
f <sub>T</sub>	transition frequency	$I_C = -10 \text{ mA}; V_{CE} = -5 \text{ V}; f = 100 \text{ MHz}$	100	_	_	MHz
F	noise figure	$I_{C} = -200 \ \mu A; \ V_{CE} = -5 \ V; \ R_{S} = 2 \ k\Omega; \ f = 1 \ kHz; \ B = 200 \ Hz$	_	_	10	dB

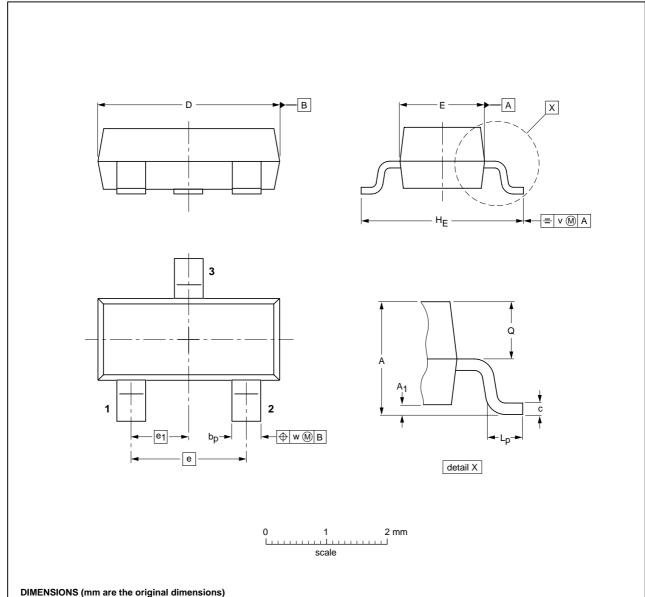
## PNP general purpose transistors

BCW29; BCW30

#### **PACKAGE OUTLINE**

#### Plastic surface-mounted package; 3 leads

SOT23



DIMENS	ЮИЗ (П	ım are tı	ne origir	nai dime	nsions)	

UNIT	Α	A <sub>1</sub> max.	bp	С	D	E	е	e <sub>1</sub>	HE	Lp	Q	v	w
mm	1.1 0.9	0.1	0.48 0.38	0.15 0.09	3.0 2.8	1.4 1.2	1.9	0.95	2.5 2.1	0.45 0.15	0.55 0.45	0.2	0.1

OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE
SOT23		TO-236AB				<del>-04-11-04</del> 06-03-16

### PNP general purpose transistors

BCW29; BCW30

#### **DATA SHEET STATUS**

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

#### **Notes**

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#### **Customer notification**

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

#### **Contact information**

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